



PK1132 (v1.0) July 22, 2021

100% Material Declaration Data Sheet for CoolRunner-II VQ100 Package

Average Weight : 0.5150 g

| Component | Substance Description | CAS # or Description | % of component | Use in product | Component weight / substance weight (in grams) | Component % of total |
|---------------|-------------------------------------------------------------------------------------------------------------------------------------|----------------------|----------------|----------------|-------------------------------------------------|----------------------|
| Silver Epoxy | | | | | 0.002221 | 0.43126% |
| | Silver | 7440-22-4 | 85.3 | | 0.001895 | |
| | Epoxy resin | Trade Secret | 5.4 | | 0.000120 | |
| | Organic anhydride | Trade Secret | 3.1 | | 0.000069 | |
| | A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol; 4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2,6-bis(2,3-epoxypropyl)phenoxy)-2-hydroxyp | - | 3.1 | | 0.000069 | |
| Anhydride | Trade Secret | 3.1 | | 0.000069 | | |
| Die | | | | | 0.013086 | 2.54097% |
| | Silicon | 7440-21-3 | 100.00 | | 0.013086 | |
| Gold Wire | | | | | 0.001831 | 0.35553% |
| | Gold | 7440-57-5 | 99.0475 | | 0.001814 | |
| | Palladium | 7440-05-3 | 0.95 | | 0.000017 | |
| | Calcium | 7440-70-2 | 0.002 | | | |
| | Beryllium | 7440-41-7 | 0.0005 | | 0.000000 | |
| Mold Compound | | | | | 0.378058 | 73.40932% |
| | Epoxy Resin | Trade Secret | 10 | | 0.037806 | |
| | Phenol Resin | Trade Secret | 5 | | 0.018903 | |
| | Silica(Amorphous) A | 60676-86-0 | 74 | | 0.279763 | |
| | Silica(Amorphous) B | 7631-86-9 | 10 | | 0.037806 | |
| Carbon Black | 1333-86-4 | 1 | | 0.003781 | | |
| Leadframe | | | | | 0.119804 | 23.26291% |
| | Nickel Plating | 7440-02-0 | 0.325 | | 0.000389 | |
| | Palladium Plating | 7440-05-3 | 0.0175 | | 0.000021 | |
| | Gold Plating | 7440-57-5 | 0.004 | | 0.000005 | |
| | Copper | 7440-50-8 | 95.5535 | | 0.114477 | |
| | Magnesium | 7439-95-4 | 0.175 | | 0.000210 | |
| | Silicon | 7440-21-3 | 0.725 | | 0.000869 | |
| Nickel | 7440-02-0 | 3.2 | | 0.003834 | | |

Revision History

| Date | Version | Description of Revisions |
|-----------|---------|-----------------------------------|
| 7/22/2021 | 1.0 | Initial Xilinx release (XCN18024) |

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